

Parameter	Symbol	Rating	Units	
Load Voltage	VL	100	V	
Load Current	lι	1.25	Α	
On-Resistance	Ron	0.13	Ω	
I/O Breakdown Voltage	V/IO	2500	Vrms	





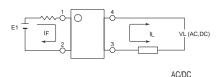
(Unit: mm)

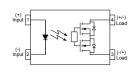






E534710





- 1. LED Anode
- 2. LED Cathode
- 3.4. Drain(MOS FET)



## **APSEMI PhotoRelays**

APSEMI Photorelays are the most reliable, technically advanced logic-to-power interface devices. Their basic function is to take a low current signal from a microprocessor to control the switching of both AC and DC loads, while providing an isolation barrier between logic and power. While this function is common to all relays, Photorelays provide distinct advantages over their mechanical counterparts including:

- Long life (No limit on mechanical and electrical
- lifetime)Bounce-free switching
- Higher speed and high frequency switching
- Higher sensitivity (less power consumption)
- Immunity to EMI or RFI

- No have voltaic arc, bounce, and noise More
- resistant to vibration and impact AC or DC load
- switching
- Small package size

#### **Function**

APSEMI PhotoRelays operate by taking a low level input current (<5mA) that energizes an input Infrared LED, which is optically-coupled to a Photo-diode array chip. This IC in turn generates a photo voltage that powers two MOSFETs typically connected in a source-to-source con | guration, allowing for both AC and DC output loads. Photorelay basically move photons to accomplish their switching function, they incur no mechanical wear and tear, providing consistent reliable switching.

# **Applications**

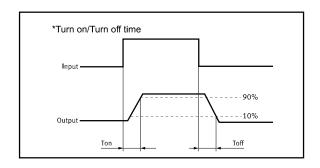
These advantages make APSEI Photorelays the ideal choice for:

- Telecom/Datacom switching
- Multiplexers
- Meter reading systems
- Data acquisition
- Medical equipment
- Battery monitoring
- I/O Sub-Systems

- Robotics
- Aerospace
- Home/Safety security systems
- **Process Control**
- **Energy Management**
- Reed Relay EMR Replacement
- Programmable Controllers

### **TPYES**

Catagoni	Output Rating		Doolsons	Part No.	Poolsing Overtity	
Category	Load Voltage	Load Current	Package	Part No.	Packing Quantity	
AC/DC	100V	1.25A	SOP-4	APY215G1S	2000pcs /reel	



Page 1



# Absolute Maximum Ratings (Ta = 25°C)

	Item	Symbol	Value	Units	Note
	Continuous LED Current	lF	50	mA	
Input	Peak LED Current	IFP	1000	mA	f=100Hz, duty=1%
	LED Reverse Voltage	VR	5	V	
	Input Power Dissipation	Pın	75	mW	
Output	Load Voltage	V∟	100	V(AC peak or DC)	
	Load Current	l.	1.25	Α	
	Peak Load Current	Peak	3.0	Α	100ms(1 pulse)
	Output Power Dissipation	Pout	350	mW	
Total Power	Dissipation	Р⊤	400	mW	
I/O Breakdov	wn Vo <b>l</b> tage	V <sub>I/O</sub>	2500	Vrms	RH=60%, 1min
Operating Te	emperature	Topr	-40 to 85	°C	
Storage Tem	nperature	T <sub>stg</sub>	-40 to 100	°C	
Pin Soldering	g Temperature	T <sub>sol</sub>	260	°C	10 sec max.

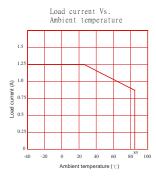
# Electrical Characteristics (Ta = 25°C)

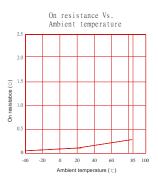
	Item	Symbol	MIN.	TYP.	MAX.	Units	Conditions
Input	LED Forward Voltage	VF		1.2	1.5	V	I⊧=10mA
	Operation LED Current	Fon		0.5	3.0	mA	
	Recovery LED Current	Foff		0.35	0.5	mA	
	Recovery LED Voltage	V <sub>Foff</sub>	0.7			V	
Output Off-Sta							I⊧=5mA,I∟=100mA,
	On-Resistance	Ron		0.13	0.25	Ω	Time to flow is within 1 sec.
	Off-State Leakage	Leak	0.01	0.02	0.10	uA	V∟=Rating
	Current		0.01	0.02	0.10	J., 1	
	Output Capacitance	Cout		90		pF	V∟=0, f=1MHz
Transmis	Turn-On Time	Ton		0.80	2.5	ms	I⊧=5mA, I∟=100mA,
sion	Turn-Off Time	Toff		0.06	0.3	ms	
Coupled	I/O Isolation Resistance	R <sub>I/O</sub>	10 <sup>10</sup>			Ω	DC500V
Coupled	I/O Capacitance	Ci/o		0.8	1.5	pF	f=1MHz

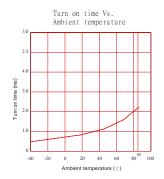
Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value): IF ≥5mA and ≤30mA

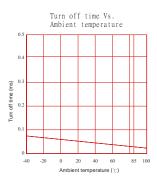


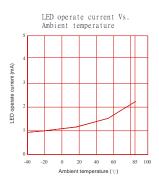
# **Engineering Data**

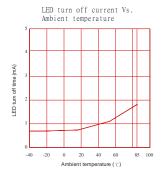


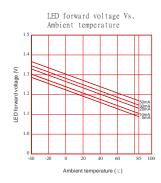


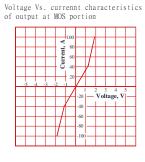


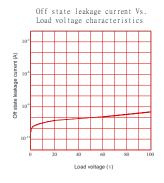


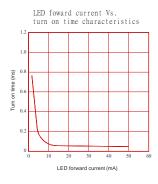


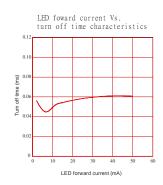


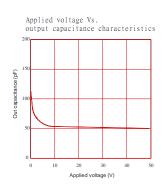








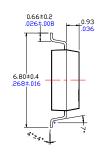


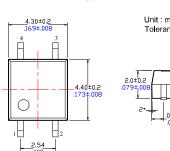




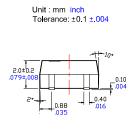
# **Dimensions and Package**

# Marking H H APY 215G1 YY=YEAR WW=WEEK WEEK





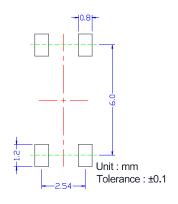
Surface mount terminal type



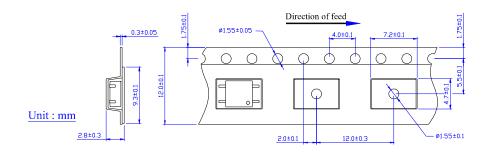
Lable

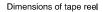


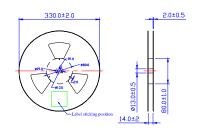
Recommended mounting pad (Top view)

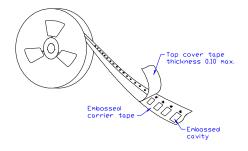


## Tape dimensions





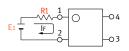


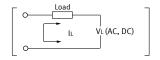




# **Using Methods**

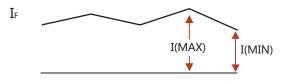
Examples of resistance value to control LED forward current (IF=5mA)





R1 (Approx)				
300 Ω				
600 Ω				
1.9ΚΩ				
4.1K Ω				

LED forward current must be more than 5mA , at I(MIN) ,and less than 30mA , at I(MAX).



## **Recommended Operating Conditions**

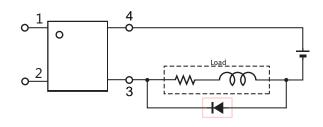
Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value):

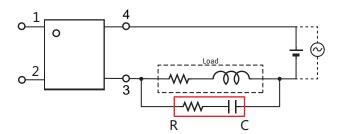
Characteristic	Symbol	Min	Тур.	Max	Unit
Forward current	lF	5.0	7.0	30	mA

#### **Protection Circuit**

Clamp diode is connected in parallel with the load. Absorb capacity with external diode.

CR Snubber is connected in parallel with the load. Absorb capacity with buffer capacity.





When adding diodes, buffer circuits (C-R), and other protections, they need to be installed near the MOS RELAY to be effective. Adding protection elements may result in a slow reset time, so adjust them according to the actual situation before use.

Note: When developing designs using this product, perform the expected performance of the equipment under the operating conditions recommended by the guidelines in this document. Continuous use under heavy loads (including, but not limited to, the application of high temperatures/current/voltage and significant changes in temperature, etc.) may result in deterioration of the reliability of this product.



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